



17258

PATENT

In re application of:

TAGUCHI ET AL

Serial No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE FOR REFLOW SOLDERING

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Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

A supplemental response in the above-identified patent application is attached.

[] No additional claim fee is required.

[X] The claim fee has been calculated as shown below:

(Col. 1)		(Col. 2)		(Col. 3)	SMALL ENTITY		OTHER THAN A SMALL ENTITY	
////////	CLAIMS	////////	HIGHEST					
////////	REMAINING	////////	NO.					
////////	AFTER	////////	PREVIOUSLY	PRESENT		ADDIT.		ADDIT.
////////	AMENDMENT	////////	PAID FOR	EXTRA	RATE	FEE	RATE	FEE
TOTAL	* 24	MINUS	** 20	= 4	x 9=	\$	x 18=	\$ 72
INDEP	* 3	MINUS	*** 3	= 0	x 42=	\$	x 84=	\$ 0
FIRST PRESENTATION OF MULT. DEP. CLAIM					+140	\$	+280=	\$
					TOTAL	\$	TOTAL	\$ 72

* If entry in Col. 1 is less than that in Col. 2, write "0" in Col. 3.

** If the highest no. previously paid for IN THIS SPACE is less than 20, write "20" in this space.

*** If the highest no. previously paid for IN THIS SPACE is less than 3, write "3" in this space.

- [X] A check in the amount of \$72.00 is attached in payment of the fee for additional claims.
- [] Please charge Deposit Account No. 50-1079 in the amount of \$.
- [X] The Commissioner is authorized to charge any deficiency in the following fees associated with this communication and to credit any excess payment to Deposit Account No. 50-1079. A duplicate copy of this letter is attached.
- [X] Any filing fees pursuant to 37 CFR §1.16 for the presentation of extra claims.
- [] Any patent application processing fees pursuant to 37 CFR §1.17, including extension of time fees pursuant to 37 CFR §1.17(a)-(d).

Respectfully submitted,



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